

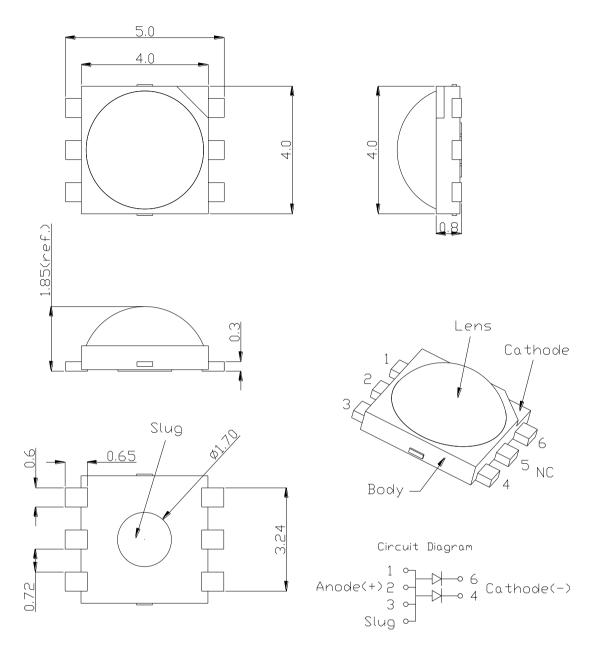
ProLight PP6N-TLxE 0.2W Power LED Technical Datasheet Version: 3.1

- High flux per LED
- Various colors
- Good color uniformity
- Industry best moisture senstivity level JEDEC Level 1
- Lead free reflow soldering
- More energy efficient than incandescent and most halogen lamps
- Low Voltage DC operated
- Instant light (less than 100ns)
- No UV

Typical Applications

- Reading lights (car, bus, aircraft)
- Portable (flashlight, bicycle)
- Uplighters/Downlighters
- Decorative/Entertainment
- Bollards/Security/Garden
- Cove/Undershelf/Task
- Indoor/Outdoor Commercial and Residential Architectural
- Automotive Ext (Stop-Tail-Turn, CHMSL, Mirror Side Repeat)
- LCD backlights

Emitter Mechanical Dimensions



Notes:

- 1. The cathode side of the device is denoted by the chamfer on the part body.
- 2. Electrical insulation between the case and the board is required. Do not electrically connect either the anode or cathode to the slug.
- 3. Drawing not to scale.
- 4. All dimensions are in millimeters.
- 5. Unless otherwise indicated, tolerances are \pm 0.10mm.
- 6. Please do not bend the leads of the LED, otherwise it will damage the LED.
- 7. Please do not use a force of over 3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.

*The appearance and specifications of the product may be modified for improvement without notice.

Flux Characteristics at 60mA, T_J = 25°C

Padiation Part Number		Dont November	Lumious Flux Φ_{V} (lm)		
Radiation Pattern	Color	Part Number Emitter	@60ı	mA	Refer @80mA
rattern		Emitter	Minimum	Typical	Typical
	Red	PP6N-TLRE	6.3	9.2	12
Lambertian	Amber	PP6N-TLAE	8.2	10	12.6
Lambertian	Green	PP6N-TLGE	10.7	12.8	16.2
	Blue	PP6N-TLBE	2.9	3.7	4.8
Lambordan					

[•] ProLight maintains a tolerance of ± 10% on flux and power measurements.

Electrical Characteristics at 60mA, T_J = 25°C

Color	Fo	rward Voltage V _F	Thermal Resistance	
Color	Min.	Тур.	Max.	Junction to Slug (°C/W)
Red	1.9	2.2	3.0	60
Amber	1.9	2.2	3.0	60
Green	3.0	3.4	3.8	60
Blue	3.0	3.4	3.8	60

ullet ProLight maintains a tolerance of \pm 0.1V for Voltage measurements.

Optical Characteristics at 60mA, T_J = 25°C

Color	Don	inant Wavelength	ι λ _D	Total included Angle (degrees)	Viewing Angle (degrees)
	Min.	Тур.	Max.	$\theta_{0.90V}$	2 θ _{1/2}
Red	613.5 nm	623 nm	631 nm	160	140
Amber	587 nm	592 nm	597 nm	160	140
Green	515 nm	525 nm	535 nm	160	140
Blue	455 nm	465 nm	475 nm	160	140

[•] ProLight maintains a tolerance of ± 1nm for dominant wavelength measurements.

[•] Please do not drive at rated current more than 1 second without proper heat sink.

Absolute Maximum Ratings

Parameter Red/Amber/Green/Blue

DC Forward Current (mA)	80
Peak Pulsed Forward Current (mA)	120 (less than 1/10 duty cycle@1KHz)
Average Forward Current (mA)	60
ESD Sensitivity	> ±500V
(HBM per MIL-STD-883E Method 3015.7)	> ±300 V
LED Junction Temperature	120°C
Operating Board Temperature at Maximum DC Forward Current	-40°C - 90°C
Storage Temperature	-40°C - 120°C
Soldering Temperature	JEDEC 020c 260°C
Allowable Reflow Cycles	3
Reverse Voltage	Not designed to be driven in reverse bias

Photometric Luminous Flux Bin Structure

Color	Bin Code	Minimum Photometric Flux (Im)	Maximum Photometric Flux (Im)	Available Color Bins
	J	6.3	8.2	All
Red	К	8.2	10.7	All
	L	10.7	13.9	[1]
Amber	К	8.2	10.7	All
	L	10.7	13.9	[1]
Green	L	10.7	13.9	All
Green	М	13.9	18.1	[1]
Pluo	F	2.9	3.8	A, 1 ^[1]
Blue	G	3.8	4.9	[1]

- ullet ProLight maintains a tolerance of \pm 10% on flux and power measurements.
- The flux bin of the product may be modified for improvement without notice.
- ^[1] The rest of color bins are not 100% ready for order currently. Please ask for quote and order possibility.

Dominant Wavelength Bin Structure

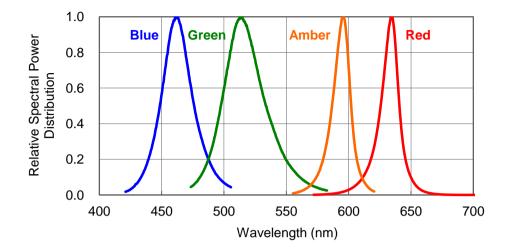
Color	Bin Code	Minimum Dominant Wavelength (nm)	Maximum Dominant Wavelength (nm)
Red	2	613.5	620.5
Reu	4	620.5	631.0
	2	587.0	589.5
A made a v	4	589.5	592.0
Amber	6	592.0	594.5
	7	594.5	597.0
	А	515	520
Croon	1	520	525
Green	2	525	530
	3	530	535
	А	455	460
Dive	1	460	465
Blue	2	465	470
	3	470	475

[•] ProLight maintains a tolerance of ± 1nm for dominant wavelength measurements.

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.

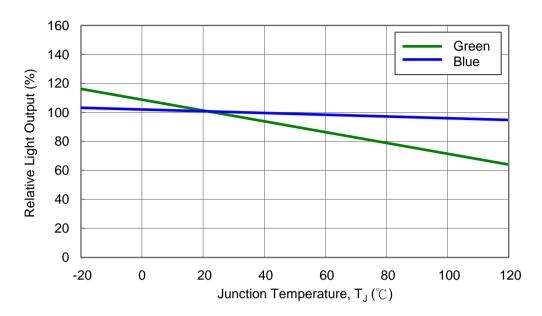
Color Spectrum, $T_J = 25^{\circ}C$

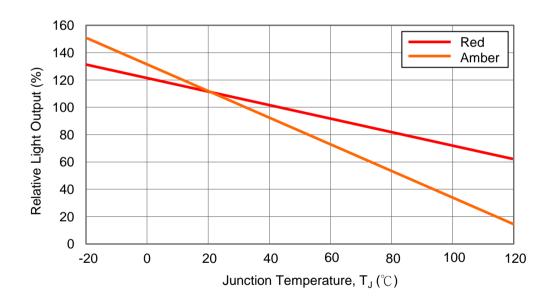
1. Blue · Green · Amber · Red



Light Output Characteristics

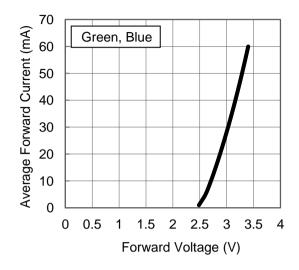
Relative Light Output vs. Junction Temperature at 60mA

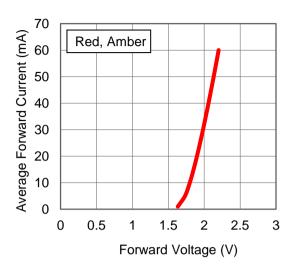




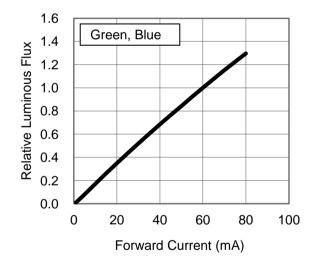
Forward Current Characteristics, T_J = 25°C

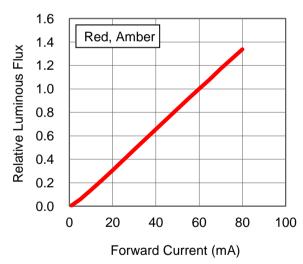
1. Forward Voltage vs. Forward Current





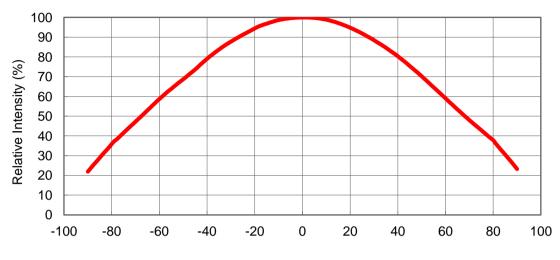
2. Forward Current vs. Normalized Relative Luminous Flux





Typical Representative Spatial Radiation Pattern

Lambertian Radiation Pattern



Moisture Sensitivity Level - JEDEC Level 1

				Soak Req	uirements	
Level	Floo	r Life	Stan	dard	Accelerated	Environment
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	≤30°C /	168 +5/-0	85°C /	NA	NA
!	Omminited	85% RH	100 +5/-0	85% RH	INA	INA

- The standard soak time includes a default value of 24 hours for semiconductor manufature's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.
- Table below presents the moisture sensitivity level definitions per IPC/JEDEC's J-STD-020C.

				Soak Req	uirements	
Level	Level Floor Life		Stan	dard	Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	≤30°C /	168 +5/-0	85°C /	NA	NA
1	Offillitilled	85% RH	100 +5/-0	85% RH	INA	INA
2	1 year	≤30°C /	168 +5/-0	85°C /	NA	NA
	i yeai	60% RH	100 +5/-0	60% RH	INA	NA
2a	4 weeks	≤30°C /	696 +5/-0	30°C /	120 +1/-0	60°C /
Za	4 WEEKS	60% RH	090 +5/-0	60% RH	120 +1/-0	60% RH
3	168 hours	≤30°C /	192 +5/-0	30°C /	40 +1/-0	60°C /
3	100 110015	60% RH	192 +5/-0	60% RH	40 +1/-0	60% RH
4	72 hours	≤30°C /	96 +2/-0	30°C /	20 +0.5/-0	60°C /
4	72 110013	60% RH	90 +2/-0	60% RH	20 +0.5/-0	60% RH
5	48 hours	≤30°C /	72 +2/-0	30°C /	15 +0.5/-0	60°C /
3	40 110015	60% RH	72 +2/-0	60% RH	13 +0.5/-0	60% RH
5a	24 hours	≤30°C /	48 +2/-0	30°C /	10 +0.5/-0	60°C /
Ja	24 Hours	60% RH	40 +2/-0	60% RH	10 +0.5/-0	60% RH
6	Time on Label	≤30°C /	Time on Label	30°C /	NA	NA
0	(TOL)	60% RH	(TOL)	60% RH	13/7	IVA

Qualification Reliability Testing

Stress Test	Stress Conditions	Stress Duration	Failure Criteria
Room Temperature Operating Life (RTOL)	25°C, I _F = max DC (Note 1)	1000 hours	Note 2
Wet High Temperature Operating Life (WHTOL)	85°C/60%RH, I _F = max DC (Note 1)	1000 hours	Note 2
Wet High Temperature Storage Life (WHTSL)	85°C/85%RH, non-operating	1000 hours	Note 2
High Temperature Storage Life (HTSL)	110°C, non-operating	1000 hours	Note 2
Low Temperature Storage Life (LTSL)	-40°C, non-operating	1000 hours	Note 2
Non-operating Temperature Cycle (TMCL)	-40°C to 120°C, 30 min. dwell, <5 min. transfer	200 cycles	Note 2
Non-operating Thermal Shock (TMSK)	-40°C to 120°C, 20 min. dwell, <20 sec. transfer	200 cycles	Note 2
Mechanical Shock	1500 G, 0.5 msec. pulse, 5 shocks each 6 axis		Note 3
Natural Drop	On concrete from 1.2 m, 3X		Note 3
Variable Vibration Frequency	10-2000-10 Hz, log or linear sweep rate, 20 G about 1 min., 1.5 mm, 3X/axis		Note 3
Solder Heat Resistance (SHR)	260°C ± 5°C, 10 sec.		Note 3
Solderability	Steam age for 16 hrs., then solder dip at 260°C for 5 sec.		Solder coverage on lead

Notes:

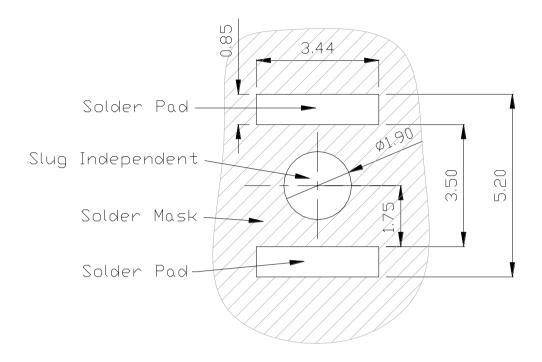
- 1. Depending on the maximum derating curve.
- 2. Criteria for judging failure

Item	Test Condition	Criteria for Judgement		
item	rest Condition	Min.	Max.	
Forward Voltage (V _F)	$I_F = max DC$	-	Initial Level x 1.1	
Luminous Flux or Radiometric Power (Φ_{V})	I _F = max DC	Initial Level x 0.7	-	
Reverse Current (I _R)	$V_R = 5V$	-	50 μA	

^{*} The test is performed after the LED is cooled down to the room temperature.

3. A failure is an LED that is open or shorted.

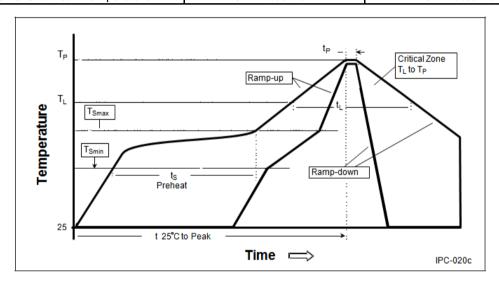
Recommended Solder Pad Design



- All dimensions are in millimeters.
- Electrical isolation is required between Slug and Solder Pad.

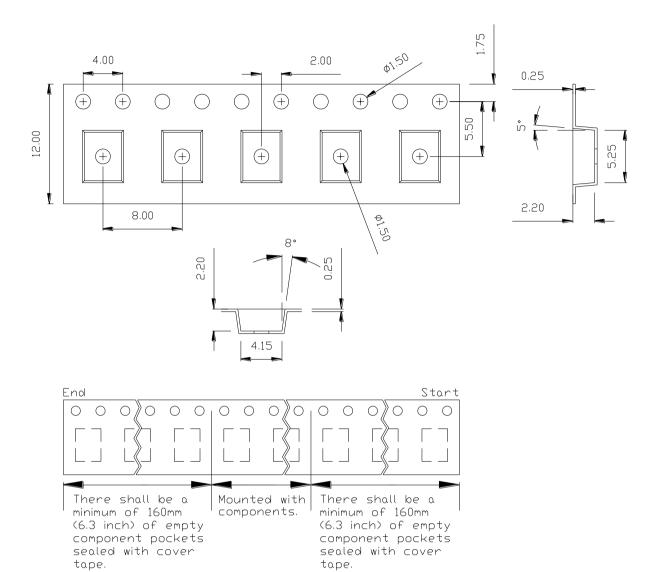
Reflow Soldering Condition

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (T _{Smax} to T _P)	3°C / second max.	3°C / second max.
Preheat		
– Temperature Min (T _{Smin})	100°C	150°C
– Temperature Max (T_{Smax})	150°C	200°C
– Time (t_{Smin} to t_{Smax})	60-120 seconds	60-180 seconds
Time maintained above:		
– Temperature (T_L)	183°C	217°C
– Time (t _L)	60-150 seconds	60-150 seconds
Peak/Classification Temperature (T _P)	240°C	260°C
Time Within 5°C of Actual Peak Temperature (t _P)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



- We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.
- Do not use solder pastes with post reflow flux residue>47%. (58Bi-42Sn eutectic alloy, etc) This kind of solder pastes may cause a reliability problem to LED.
- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a
 double-head soldering iron should be used. It should be confirmed beforehand whether the
 characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than three times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

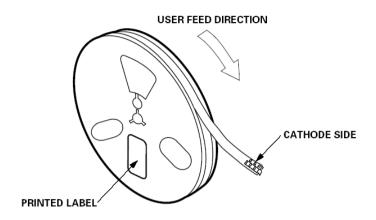
Emitter Reel Packaging

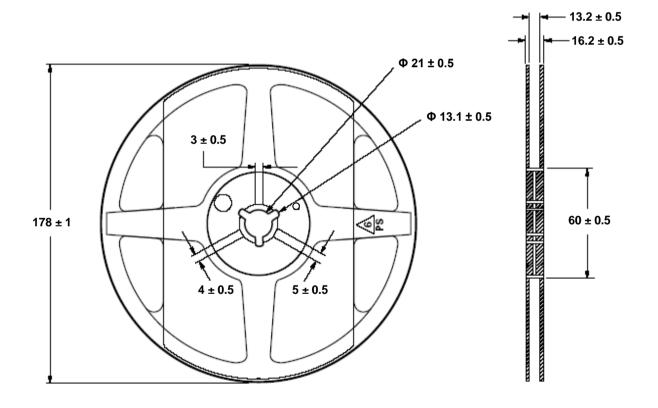


Notes:

- 1. Drawing not to scale.
- 2. All dimensions are in millimeters.
- 3. Unless otherwise indicated, tolerances are \pm 0.10mm.

Emitter Reel Packaging





Notes:

- 1. Empty component pockets sealed with top cover tape.
- 1000 pieces per reel for white.
 500, 500 and 1000 pieces per reel for others color.
- 3. Drawing not to scale.
- 4. All dimensions are in millimeters.

Precaution for Use

Storage

Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH. It is also recommended to return the LEDs to the MBB and to reseal the MBB.

- The slug is is not electrically neutral. Therefore, we recommend to isolate the heat sink.
- The LEDs are sensitive to electrostatic discharge. Appropriate ESD protection measures
 must be taken when working with the LEDs. Non-compliance with ESD protection measures
 may lead to damage or destruction of the LEDs.
- We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.
- Do not use solder pastes with post reflow flux residue>47%. (58Bi-42Sn eutectic alloy, etc) This kind of solder pastes may cause a reliability problem to LED.
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decide after considering the package maximum temperature.
- The appearance, specifications and flux bin of the product may be modified for improvement without notice. Please refer to the below website for the latest datasheets. http://www.prolightopto.com/

Handling of Silicone Lens LEDs

Notes for handling of silicone lens LEDs

- Please do not use a force of over 3kgf impact or pressure on the silicone lens, otherwise it will cause a catastrophic failure.
- The LEDs should only be picked up by making contact with the sides of the LED body.
- Avoid touching the silicone lens especially by sharp tools such as Tweezers.
- Avoid leaving fingerprints on the silicone lens.
- Please store the LEDs away from dusty areas or seal the product against dust.
- When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the silicone lens must be prevented.
- Please do not mold over the silicone lens with another resin. (epoxy, urethane, etc)

